



SS24L~SS2200L

Surface Mount Low VF Schottky Rectifiers

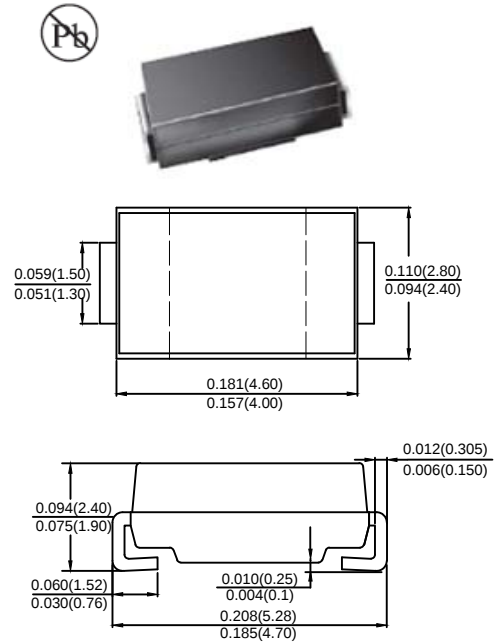
Features

- Low profile package
- Ideal for automated placement
- Ultrafast reverse recovery time
- Low power losses, high efficiency
- Low forward voltage drop
- High surge capability
- High temperature soldering:
260°C/10 seconds at terminals
- Component in accordance to
RoHS 2002/95/1 and WEEE 2002/96/EC

Mechanical Data

- **Case:** JEDEC DO-214AC (SMA) molded plastic
- **Terminals:** Solder plated, solderable per
J-STD-002B and JESD22-B102D
- **Polarity:** Laser band denotes cathode end

SMA/DO-214AC



Dimensions in inches and (millimeters)

Maximum Ratings & Thermal Characteristics

(T_A = 25 °C unless otherwise noted)

Type Number	SYMBOL	SS 24L	SS 245L	SS 26L	SS 28L	SS 210L	SS 2150L	SS 2200L	Unit
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	40	50	60	80	100	150	200	V
Maximum RMS Voltage	V _{RMS}	28	35	42	56	70	105	140	V
Maximum DC Blocking Voltage	V _{DC}	40	50	60	80	100	150	200	V
Average Rectified Output Current @T _L =100°C	I _{F(AV)}	2.0							A
Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	50							A
Rating for fusing (t<8.3ms)	I ² t	10.38							A ² s
Forward Voltage @I _F =2.0A	V _{FM}	0.45		0.55	0.75		0.85		V
Peak Reverse Current @T _A =25°C	I _R	0.1			0.05				mA
At Rated DC Blocking Voltage @T _A =100°C		10			5				
Typical Junction Capacitance (Note 2)	C _J	28							pF
Typical Thermal Resistance per leg	R _{θ JL}	88							°C /W
Operating Temperature Range	T _J	-55 to+150							°C
Storage Temperature Range	T _{STG}	-55 to +150							°C

Note: 1.Pulse Test with PW=300usec,1%Duty Cycle.

2.Mounted on P.C.Board with 5.0 mm² (0.13mm thick) copper pad areas.



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Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

Fig. 1 Forward Current Derating Curve

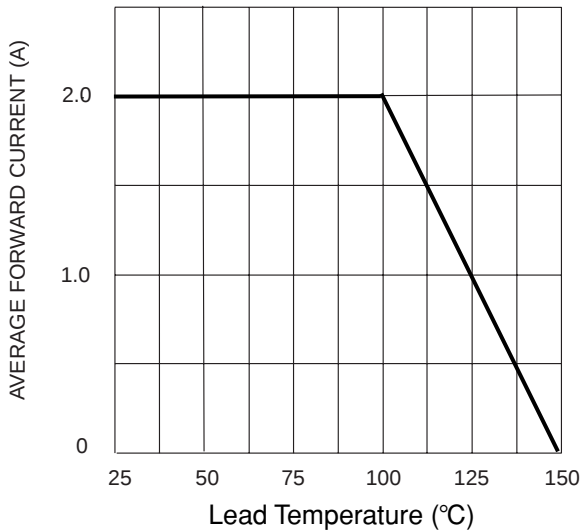


Fig. 2 Typ. Forward Characteristics

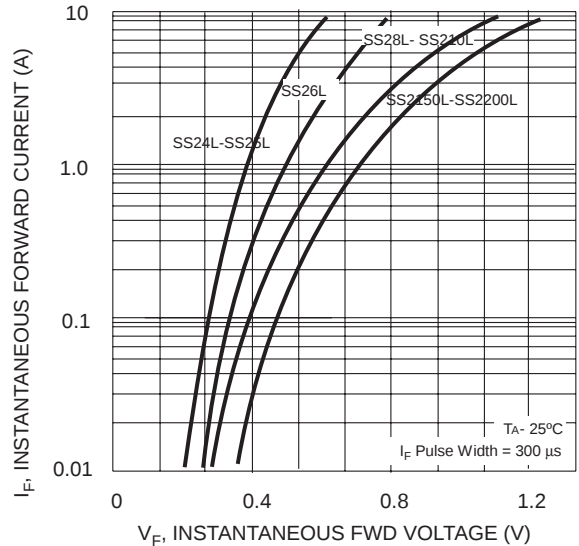


Fig. 3 Max Non-Repetitive Peak Fwd Surge Current

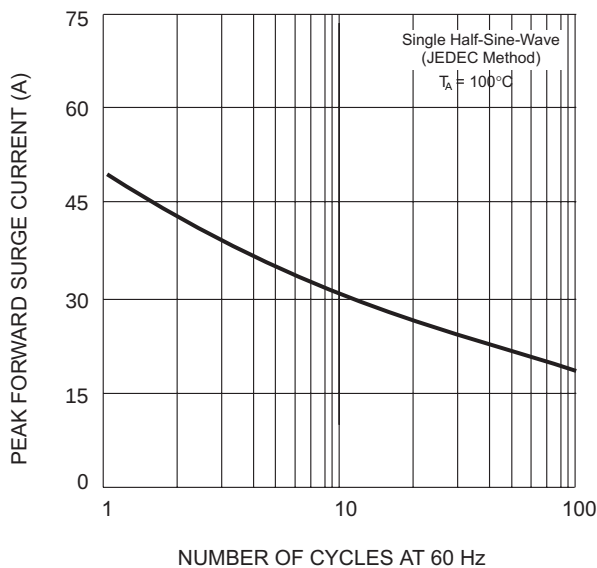
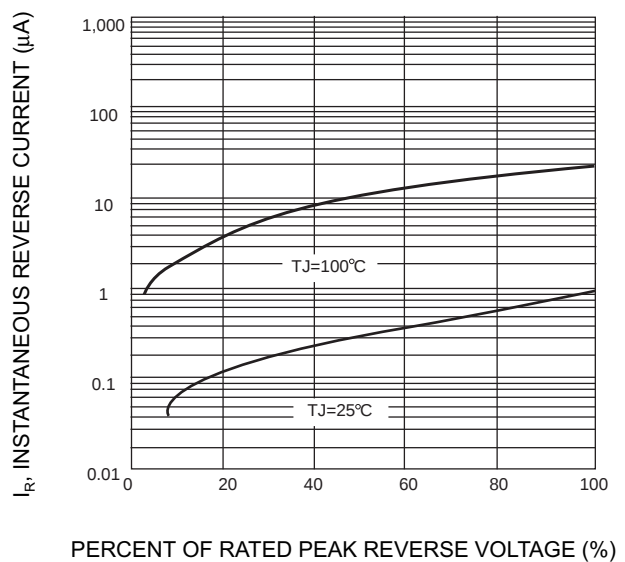


Fig. 4 Typical Reverse Characteristics (per element)



SMA PAD LAYOUT

